

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hsien-Wei Chen	04/25/2007
Shih-Hsun Hsu	04/25/2007
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77, R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11745595
CORRESPONDENCE DATA	
Fax Number:	(770)951-0933
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	770-933-9500
Email:	dan.mcclure@tkhr.com
Correspondent Name:	Daniel R. McClure
Address Line 1:	100 Galleria Parkway
Address Line 2:	Suite 1750
Address Line 4:	Atlanta, GEORGIA 30339
ATTORNEY DOCKET NUMBER:	252011-4340
NAME OF SUBMITTER:	Daniel R. McClure
Total Attachments: 2 source=00521362#page1.tif	

OP \$40.00 11745595

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PATENT
REEL: 019261 FRAME: 0732

ASSIGNMENT

WHEREAS, Hsien-Wei CHEN and Shih-Hsun HSU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR WAFER WITH ASSISTING DICING STRUCTURE AND DICING METHOD
THREOF

Filed: _____ Serial No. _____

Executed on: April 25, 2007

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignees expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Hsien-Wei Chen
Hsien-Wei CHEN

4/25, 2007
Date:

Shih-Hsun Hsu
Shih-Hsun HSU

4/25 / 2007
Date: